

## ABSTRACT

5 A thin layer of carbide containing an ultra-hard component, such as diamond, is applied to a formed compact for a drilling tool. The compact is then subjected to a high-temperature, high-pressure process to bond it to the added layer. This process allows the use of an underlying substrate which has a lower binder content than previously possible. The compact provides superior cutting ability, as even if the diamond-enhanced layer wears through, the carbide can provide enhanced hardness.

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